SKYTEC BOLT
THE METAL BONDED DIAMOND GRINDING TOOL FOR THE POWERGRIND PROCESS
The new SKYTEC BOLT type of metal bond was specially developed for the patented Agathon PowerGrind process. Electrical discharge conditioning enables the grinding wheel to be continuously and simultaneously dressed, sharpened and cleaned during the grinding process. The maximum chip space and the permanent free-cutting wheel topography of the SKYTEC BOLT enable the tool inserts to be processed with the greatest economic efficiency.

**Shorter grinding time:** Specially adapted diamond grains and the newly developed metal bond enable the contact time to be reduced by up to 50 percent in combination with the PowerGrind process.

**Low grinding forces:** The individually adapted specification for the grinding wheel and ongoing conditioning reduces the grinding force.

**Minimal chipping:** The use of small grain sizes leads to a significant reduction in cutting edge chipping with a constant level of economic efficiency.

**Product range**

<table>
<thead>
<tr>
<th>Diameter</th>
<th>Width of the abrasive layer</th>
<th>Height of the abrasive layer</th>
<th>Specification</th>
<th>Machine type</th>
</tr>
</thead>
<tbody>
<tr>
<td>400</td>
<td>8, 10, 12, 14, 16, 18, 20</td>
<td>6</td>
<td>Depending on the application</td>
<td>Agathon Combi &amp; Penta with PowerGrind</td>
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</tbody>
</table>

**Application**

Grinding of cemented carbide, cermet and PCBN inserts

**Comparison of grinding layer**

Conditioning with an SiC or aluminium oxide wheel

- Low grain protrusion
- Diamond is fractured and mechanically affected

Conditioning using the PowerGrind process

- High grain protrusion
- Low diamond break-out and small bonding surfaces